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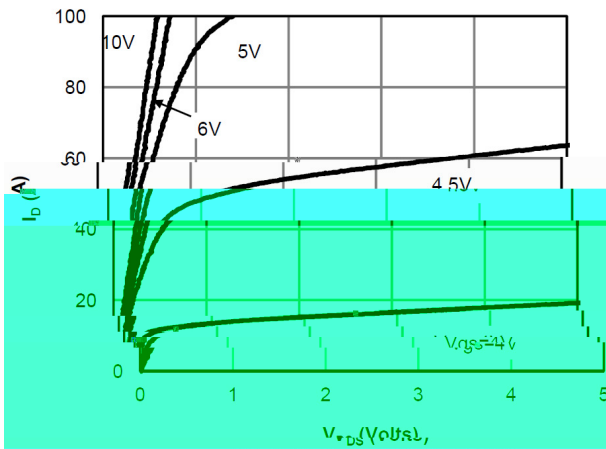


Fig 1: On-Region Characteristics

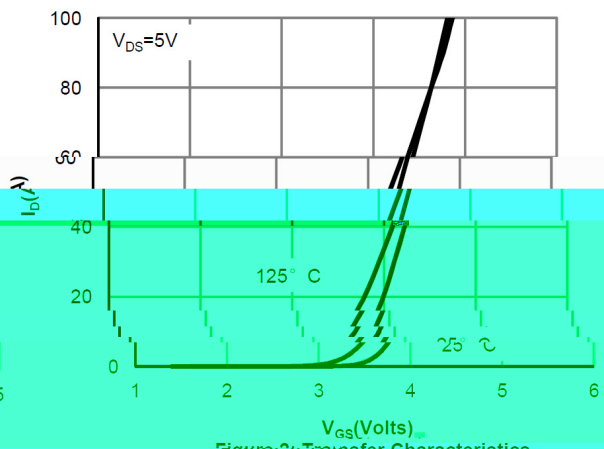


Figure 2: Transfer Characteristics

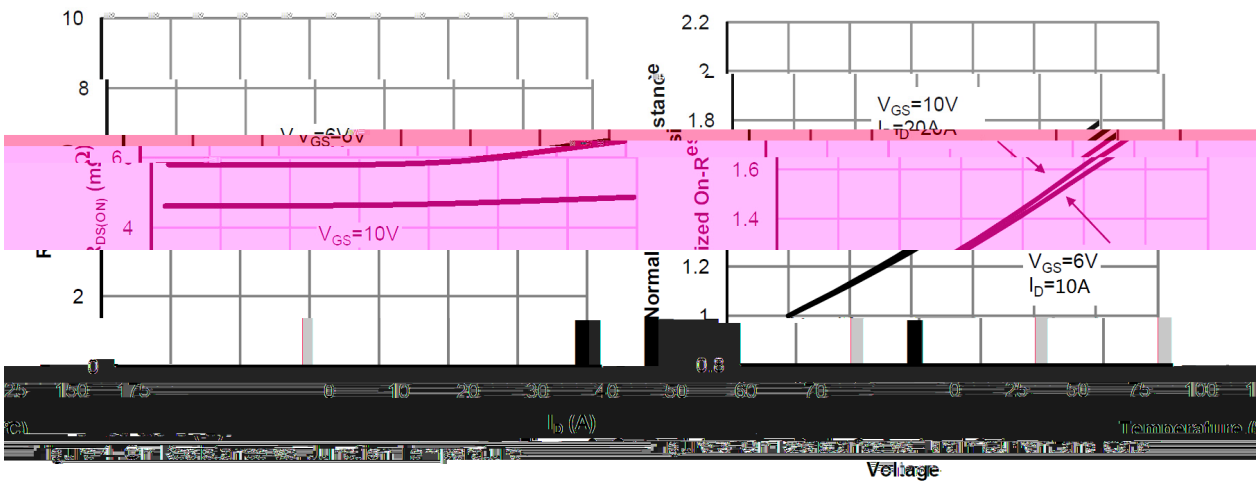


Figure 3: On-Resistance vs. Drain Current

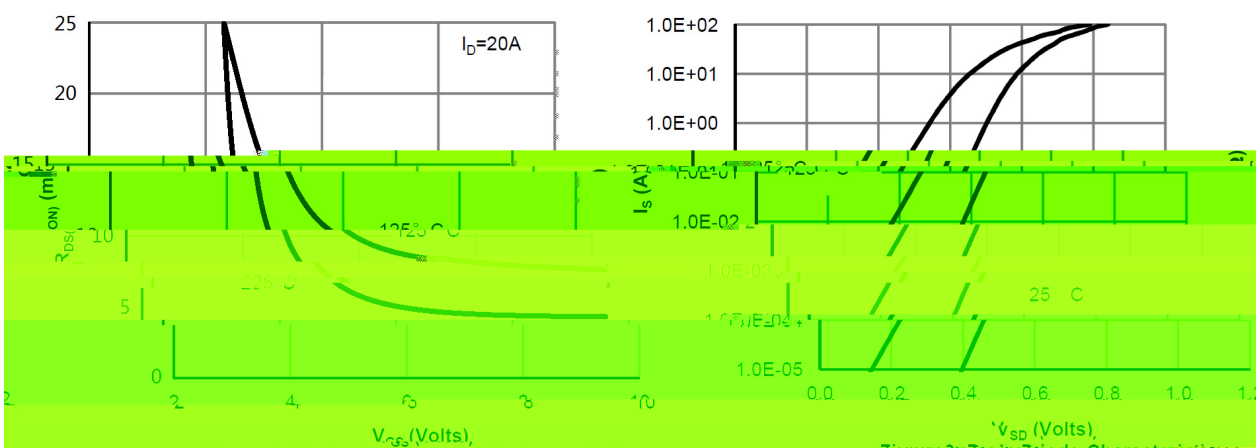


Figure 4: On-Resistance vs. Gate-Source Voltage

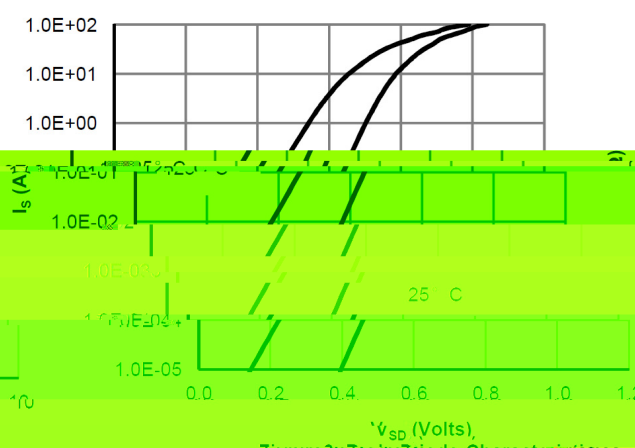


Figure 5: Body Diode Characteristics

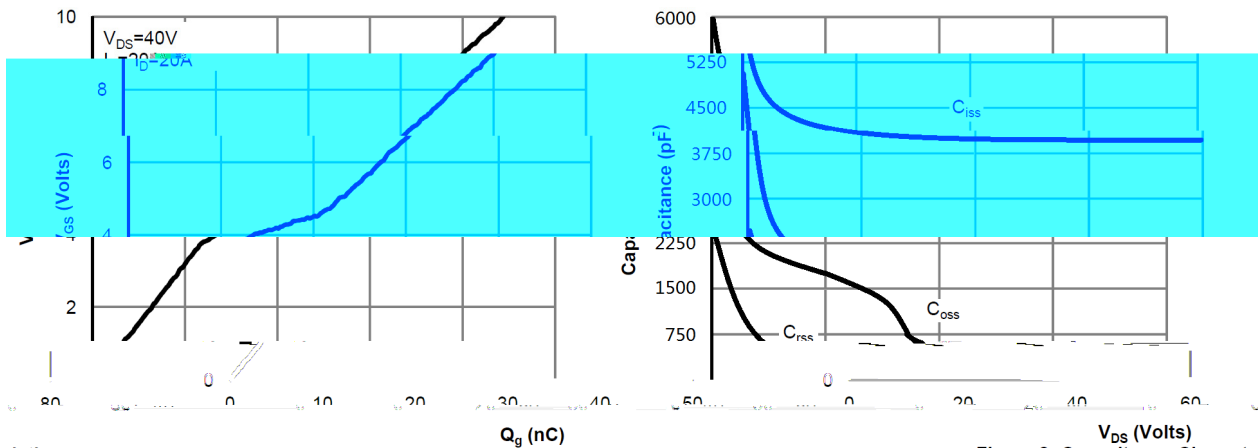


Figure 7: Gate-Charge Characteristics

Figure 8: Capacitance Characteristics

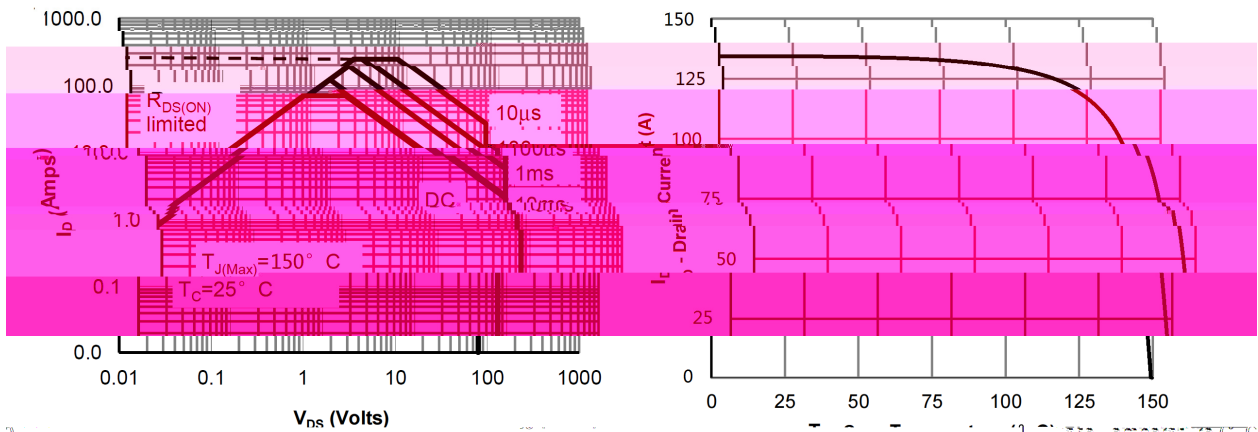


Figure 9: Maximum Power Dissipation

Figure 10: Maximum Continuous Drain Current vs Case Temperature

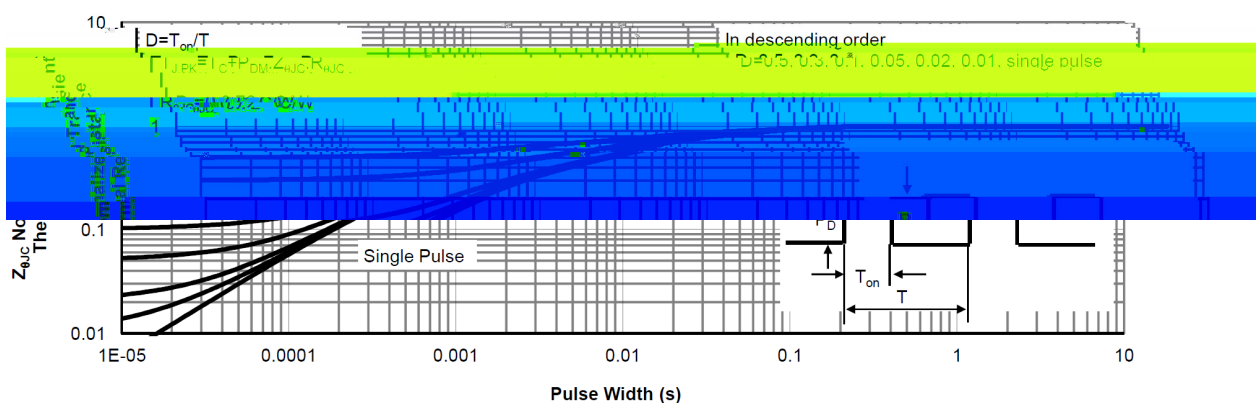
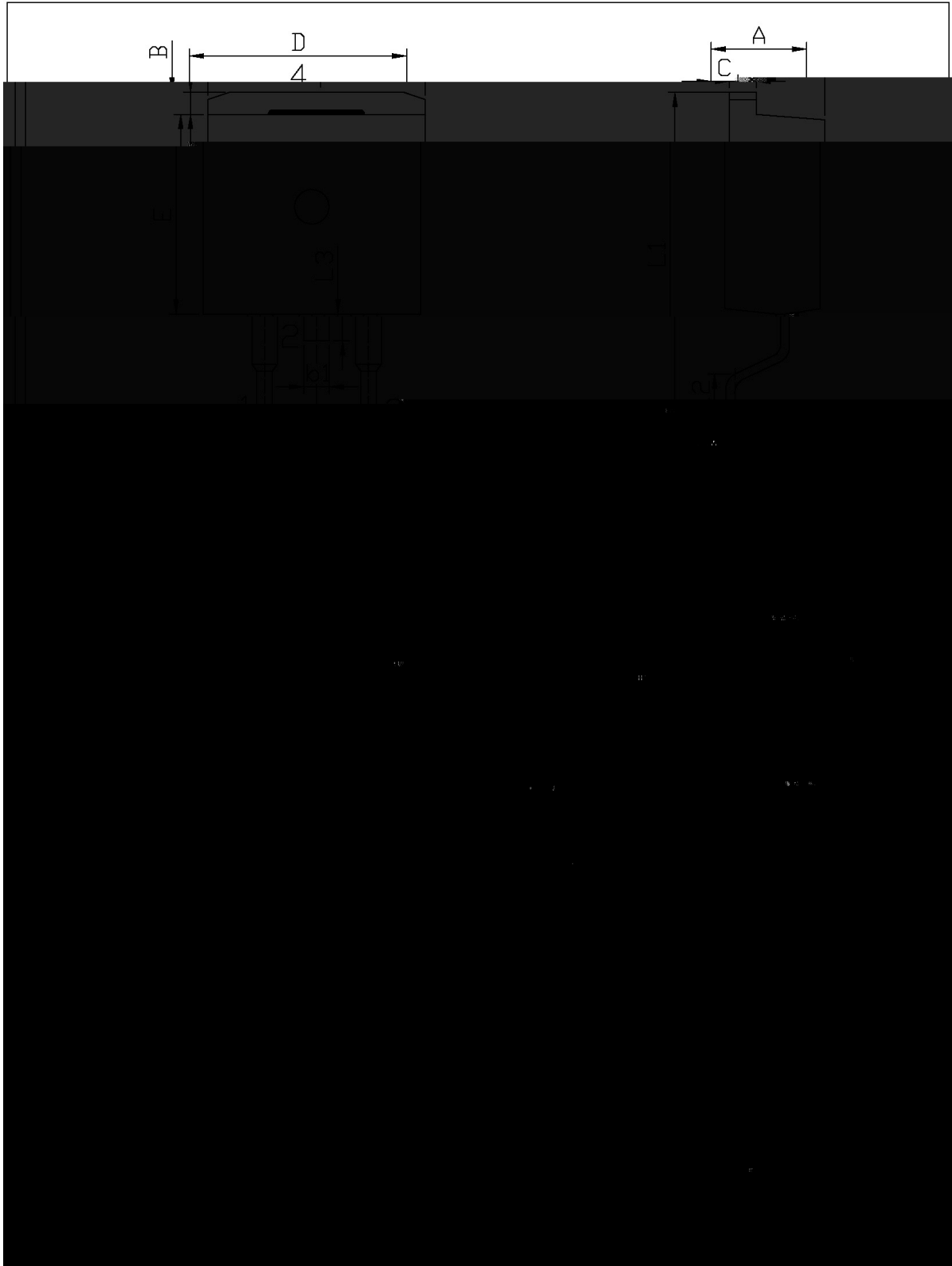
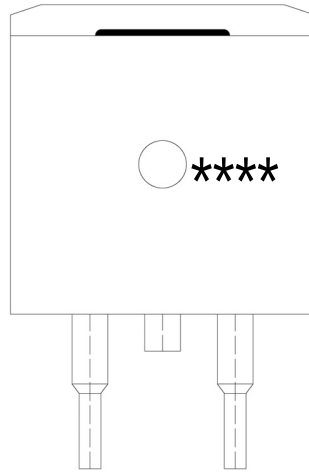


Figure 11: Normalized Maximum Transient Thermal Impedance





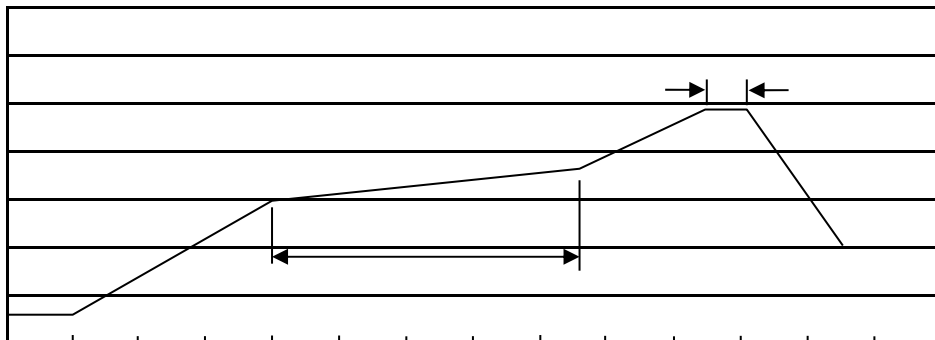
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Temperature Profile for IR Reflow Soldering(Pb-Free)



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 i` ʌ, ɔ ŷ ʌ K †

†
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 †

□ ŷ X ° † `H X °

ɔ` γ

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≈ 1 γ

	Units/Tube /	Tubes/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Tube	Inner Box	Outer Box